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1	2	("5173220").PN.	USPAT;	2003/09/25 12:56
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2	8	["4358331" "4752498" "4822536" "4863538" "4929402"	USPAT	2003/09/25 12:43
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3	3943188	metal or glass or ceramic	USPAT; US-PGPUB;	2003/09/25 12:56
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4	1782	stercolithograph\$6	USPAT;	2003/09/25 12:56
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5	1134	(metal or glass or ceramic) and stereolithograph\$6	USPAT;	2003/09/25 13:34
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7	2631039	encapsul\$5 or mold\$4 or pot\$4 or seal\$4	USPAT;	2003/09/25 13:35
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8	267	264/401.ccls. and (encapsul\$5 or mold\$4 or pot\$4 or seal\$4)	USPAT;	2003/09/25 13:38
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9	3943100	ceramic or glass or metal	USPAT; US-PGPUB;	2003/09/25 13:39
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10	267	(264/401.ccls. and (encapsul\$5 or mold\$4 or pot\$4 or scal\$4)) and	USPAT;	2003/09/25 13:38
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11	203	(264/401.ccls. and (encapsul\$5 or mold\$4 or pot\$4 or seal\$4)) and	USPAT;	2003/09/25 13:38
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12	3247516	semiconduct\$4 or electronic or chip or die	IBM_TDB USPAT;	2003/09/25 13:39
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13	107	((264/401.ccls. and (encapsul\$5 or mold\$4 or pot\$4 or seal\$4)) and	USPAT;	2003/09/25 13:39
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14	3968414	ceramic or glass or metal or hermetic	USPAT;	2003/09/25 13:40
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15	107	(ceramic or glass or metal or hermetic) and (semiconduct\$4 or electronic	USPAT;	2003/09/25 13:54
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